

TQM879008

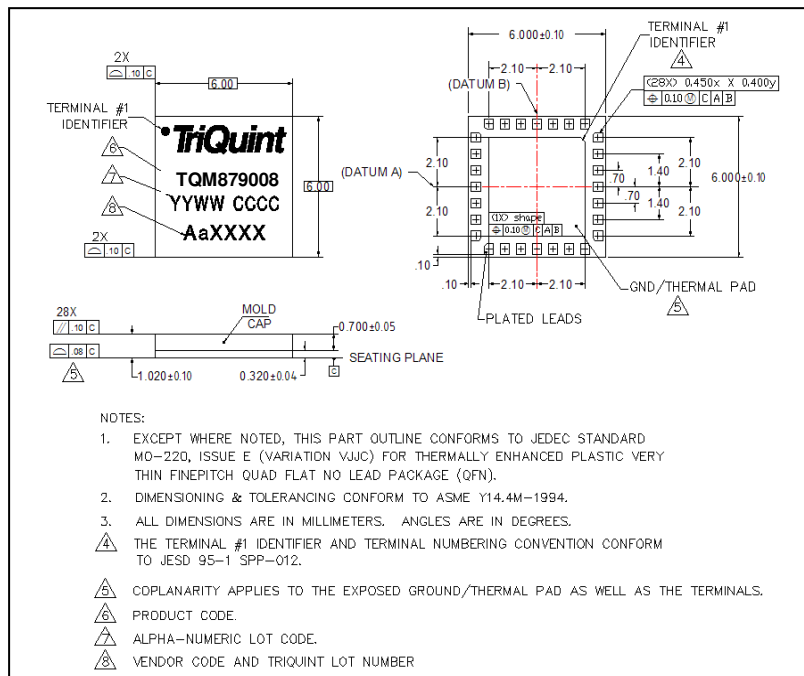
2.3-2.7GHz 1/2 W Digital Variable Gain Amplifier

Mechanical Information

Package Information and Dimensions

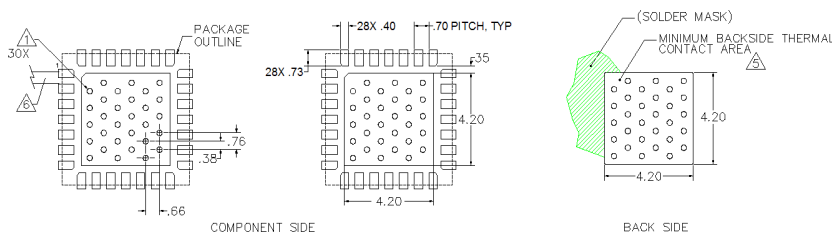
This package is RoHS-compliant. The package bottom finish is electrolytic plated Au over Ni. It is compatible with both lead-free (maximum 260 °C reflow temperature) and lead (maximum 245 °C reflow temperature) soldering processes. Also recommend adding active fluxes of 2% during solder reflow.

The component will be laser marked with “TQM879008” product label with an alphanumeric lot code on the top surface of the package.



Mounting Configuration

All dimensions are in millimeters (inches). Angles are in degrees.



NOTES:

- GROUND/THERMAL VIAS ARE CRITICAL FOR THE PROPER PERFORMANCE OF THIS DEVICE. VIAS SHOULD USE A .35mm (#80/.0135") DIAMETER DRILL AND HAVE A FINAL, PLATED THRU DIAMETER OF .25mm (.010").
- ADD AS MUCH COPPER AS POSSIBLE TO INNER AND OUTER LAYERS NEAR THE PART TO ENSURE OPTIMAL THERMAL PERFORMANCE.
- TO ENSURE RELIABLE OPERATION, DEVICE GROUND PADDLE-TO-GROUND PAD SOLDER JOINT IS CRITICAL.
- ADD MOUNTING SCREWS NEAR THE PART TO FASTEN THE BOARD TO A HEATSINK. GROUND/THERMAL VIA REGION CONTACTS THE HEATSINK.
- DO NOT PUT SOLDER MASK ON THE BACK SIDE OF THE PC BOARD IN THE REGION WHERE THE BOARD CONTACTS THE HEATSINK.
- RF TRACE WIDTH DEPENDS UPON THE PC BOARD MATERIAL CONSTRUCTION.
- USE 1 OZ. COPPER MINIMUM.
- ALL DIMENSIONS ARE IN MILLIMETERS. ANGLES ARE IN DEGREES.

Notes:

- Ground / thermal vias are critical for the proper performance of this device. Vias should use a .35mm (#80 / .0135") diameter drill and have a final plated thru diameter of .25 mm (.010").
- Add as much copper as possible to inner and outer layers near the part to ensure optimal thermal performance.